9-Channel Power Driver

HITACHI

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Description

The HA13408 9-channel power driver IC is designed to drive dot matrix printer head. This IC can drive 9 pins without using any external components. HA13408 can be used for 2 system four-phase step drive, as every channel is used independently.

Features

• High output current: 1.5 A/channel Max

• High sustaining voltage: 50 V Min

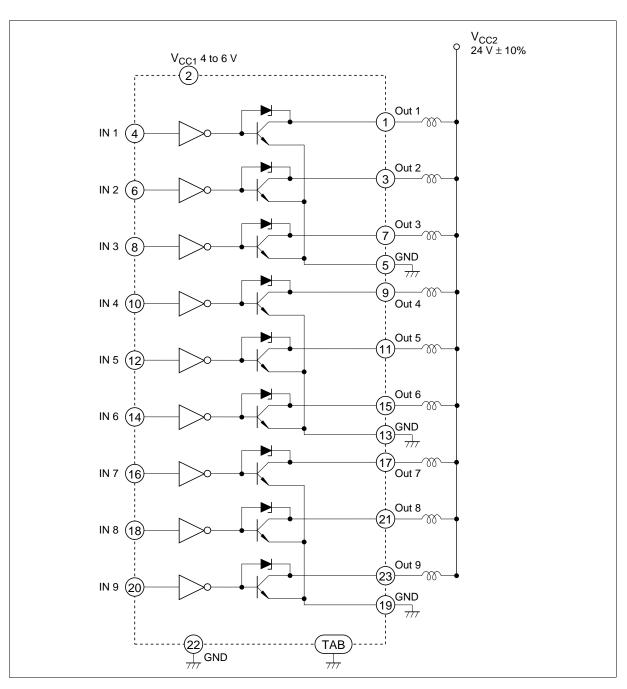
- Low saturation voltage
- Low supply current
- Low input current
- Compatible with TTL, LSTTL & 5 V CMOS
- Low thermal resistance package
- Zener diodes

Truth Table

Input	Output
Low	On
High	Off
Open	Off



Block Diagram



(2)

Peak Current and Turn-Off Time

Figure 1 shows load current (Iout) and output terminal voltage (Vout) waveforms for the HA13408 driving an inductive load.

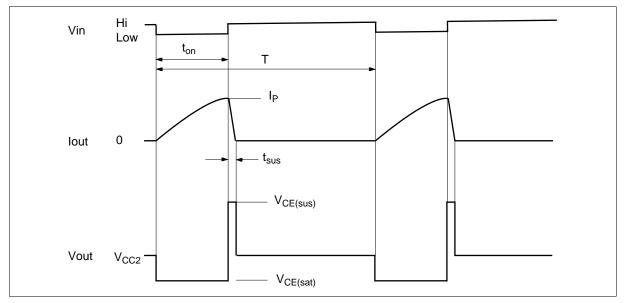


Figure 1 Output Waveforms

The peak output current (Ip) and sustain time (tsus) are obtained as follows;

$$I_{P} = \frac{V_{CC2} - V_{CE(sat)}}{R} \left(1 - \exp\left(-\frac{R}{L}t_{on}\right) \right) \doteqdot \frac{V_{CC2}}{R} \left(1 - \exp\left(-\frac{R}{L}t_{on}\right) \right)$$

$$t_{SUS} = \frac{L}{R} \ln\left(1 + \frac{I_{P} \cdot R}{V_{CE(sus)} - V_{CC2}}\right)$$
(2)

Where L is load self-inductance and R is load direct current resistance.

For example, under the following conditions:

$$L = 5 \text{ mH},$$

$$R = 22 \Omega$$

Supply voltage $V_{CC2} = 24 \text{ V}$,

Time to drive load ton = 0.42 ms.

Peak current (Ip) and sustain time (tsus) are then:

$$I_p = 0.87 A$$

$$t_{sus} = 0.118 \text{ ms}$$

Where $V_{CE(sat)} = 1.3 \text{ V typ}$ and $V_{CE(sus)} = 52 \text{ V typ}$.

Power Dissipation

Power dissipation driving an inductive load for an HA13408 is determined as follows:

First, average power dissipation (Pon) per channel at ton is obtained as follows:

Pon
$$\doteq V_{CE(sat)} I_P \left(\frac{V_{CC2}}{R \bullet I_P} - \frac{1}{t_{ON}} \frac{L}{R} \right)$$
 (3)

Average power dissipation (Psus) at t_{sus}:

$$Psus \doteq V_{CE(sus)} I_{P} \left(\frac{1}{t_{Sus}} \frac{L}{R} - \frac{V_{CE(sus)} - V_{CC2}}{R \cdot I_{P}} \right)$$
(4)

Where I_P and tsus are obtained in equations (1) and (2).

Average power dissipation (P_T) per channel for a period is obtained as follows:

$$P_T
div \frac{1}{T} (Pon \cdot t_{On} + Psus \cdot t_{SUS})$$
 (5)

Where drive period is defined as T.

Power dissipation (P_T) for 9 channels driven at the same time:

$$P_T
div \frac{9}{T} (Pon \cdot t_{On} + Psus \cdot t_{SUS})$$
 (6)

Application

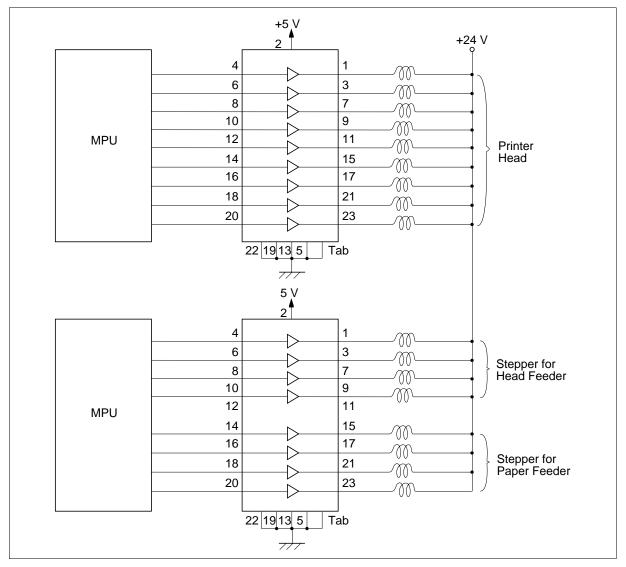


Figure 2 Dot Matrix Printer

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Rating	Unit	Notes
Supply voltage	V _{CC1}	7.0	V	
Input voltage	V _I	V_{CC1}	V	
Output voltage	$V_{\text{CE(sus)}}$	50	V	
Output current	Io	1.5	А	
Power dissipation	P_{T}	20	W	1
Junction temperature	Tj	150	°C	
Operating junction temperature range	Tjop	-20 to +125	°C	
Storage temperature range	Tstg	-55 to +125	°C	

Notes: 1. Thermal resistance

 $\theta_{j-a} \le 40^{\circ} \text{C/W}$

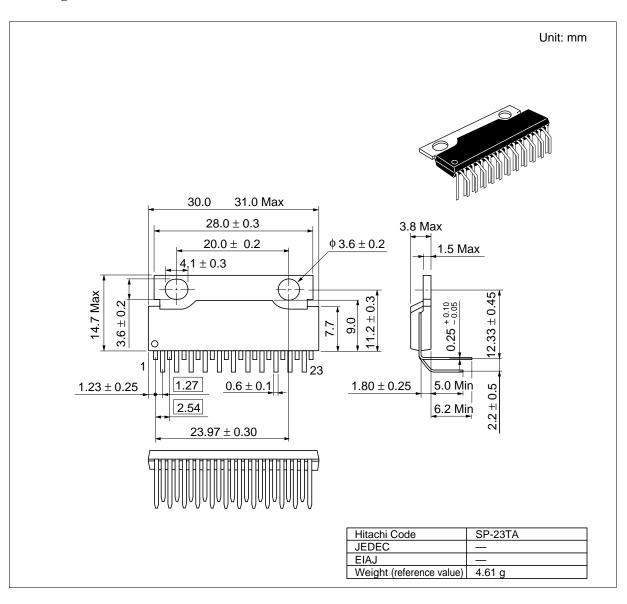
 $\theta_{i-c} \leq 3^{\circ}C/W$

Electrical Characteristics (Ta = 25°C, $V_{CC1} = 5 \text{ V}$)

Item	Symbo	l Min	Тур	Max	Unit	Test Conditions	Note
Input Low voltage	V_{IL}	_	_	0.8	V	V _{CC1} = 4.0 V	
Input High voltage	V _{IH}	2.0	_	_	V	V _{CC1} = 6.0 V	
Input Low current	I _{IL}	-100	-15	+10	μΑ	V ₁ = 0 V	
Input High current	I _{IH}	-10	0	+10	μΑ	V ₁ = 2.4 V	
Supply current	I _{cco}	_	30	45	mA	All V ₁ = 2.4 V	
	I _{cc}	_	33	50	mA	All $V_i = 0 V$	
Output cut off current	I _{CEO}	_	_	1.0	mA	$V_{CC1} = 6 \text{ V}, V_{CC2} = 40 \text{ V}, V_1 = 2.0 \text{ V}$	′
Output saturation voltage	$V_{\text{CE(sat)}}$	_	1.6	2.2	V	$V_{CC1} = 4 \text{ V}, I_0 = 1.0 \text{ A}, V_1 = 0.8 \text{ V}$	
Output sustaining voltage	$V_{\text{CE(sus)}}$	50	_	_	V	I _O = 1.0 A	1
Delay time	t _{PLH}	_	1.5	5	μs	Turn OFF	
	t _{PHL}	_	0.3	5	μs	Turn ON	

Note: 1. The conditions of loading; Measure at Ls = 5 mH, Rs = 22Ω .

Package Dimensions



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HTACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group.

Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom

Tel: <44> (1628) 585000 Fax: <44> (1628) 778322 Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218

Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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